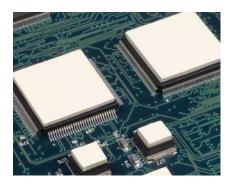
# **Gap Pad® 2500S20**

Highly Conformable, Thermally Conductive, Reinforced "S-Class" Gap Filling Material

#### **Features and Benefits**

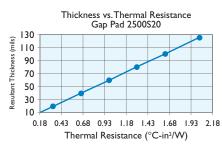
- Thermal conductivity: 2.4 W/m-K
- Low "S-Class" thermal resistance at ultra-low pressures
- Ultra conformable, "gel-like" modulus
- Designed for low-stress applications
- Fiberglass reinforced



Gap Pad 2500S20 is a thermally conductive, reinforced material rated at a thermal conductivity of 2.4 W/m-K. The material is a filled-polymer material yielding extremely soft, elastic characteristics. The material is reinforced to provide easy handling, converting, added electrical isolation and tear resistance. Gap Pad 2500S20 is well suited for low-pressure applications that typically use fixed standoff or clip mounting. The material has a conformable yet elastic nature that allows for excellent interfacing and wet-out characteristics, even to rough surfaces and/or topography.

Gap Pad 2500S20 is offered with inherent natural tack on both sides of the material allowing for stick-in-place characteristics during application assembly. The material is supplied with protective liners on both sides.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 2500S20			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Light Yellow	Light Yellow	Visual
Reinforcement Carrier	Fiberglass	Fiberglass	_
Thickness (inch) / (mm)	0.010 to 0.125	0.254 to 3.175	ASTM D374
Inherent Surface Tack (I- or 2-sided)	2	2	_
Density (g/cc)	3.1	3.1	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness, Bulk Rubber (Shore 00) (1)	20	20	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	5	35	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	_
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>3000	>3000	ASTM D149
Dielectric Constant (1000 Hz)	6.6	6.6	ASTM D150
Volume Resistivity (Ohm-meter)	1011	1011	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	2.4	2.4	ASTM D5470
I) Thirty second delay value Shore 00 hardness scale			

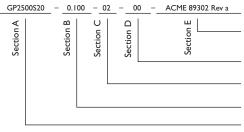
#### Typical Applications

- Between processors and heat sinks
- · Between graphics chips and heat sinks
- DVD and CDROM electronics cooling
- Area where heat needs to be transferred to a frame, chassis or other type of heat spreader.

# **Configurations Available:**

• Sheet form and die-cut parts

## **Building a Part Number**



## **Standard Options**

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level

0816 = Standard sheet size 8" x 16", or 00 = custom configuration

02 = Natural tack, both sides

Standard thicknesses available: 0.010", 0.015", 0.020", 0.040", 0.060", 0.080", 0.100", 0.125"

GP2500S20 = Gap Pad 2500S20 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others.

<sup>2)</sup> Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116